

Title (en)

A powder for use for dry activation of a substrate for electroless metallization.

Title (de)

Pulver für die trockene Aktivierung eines Substrates zur stromlosen Metallisierung.

Title (fr)

Poudre destinée à l'activation sèche d'un substrat pour le métalliser sans courant.

Publication

EP 0087135 A1 19830831 (EN)

Application

EP 83101561 A 19830218

Priority

DK 70582 A 19820218

Abstract (en)

A catalytically active powder, its preparation, and its use for activating insulating substrates to receive electrolessly deposited metal in a coherent metal layer are described. The powder of the invention comprises a plastic powder containing catalyzing/activating chemical compounds allowing that the acceleration of the catalyst is not carried out until the powder is melted down onto the substrate. The substrate need not be etched prior to the metallization since the plastic melted down ensures a good adhesion between metal and plastics and between plastics and substrate. Furthermore, the colloidal nature of the catalyzing compounds is stabilized in a particular and especially durable manner by the plastic powder. The use of the powder causes less risk to the environment since the catalyst may be applied as a dry powder, and since the etching of the substrate is avoided.

IPC 1-7

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IPC 8 full level

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IPC 8 main group level

C23C (2006.01)

CPC (source: EP)

C23C 18/28 (2013.01)

Citation (search report)

- DE 1521445 A1 19701008 - PHOTOCIRCUITS CORP
- WO 8201382 A1 19820429 - NESELCO AS [DK], et al
- DE 2613637 B2 19780720

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